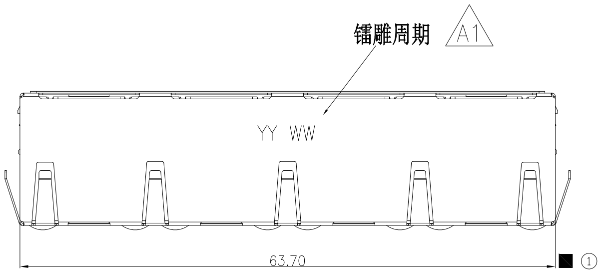
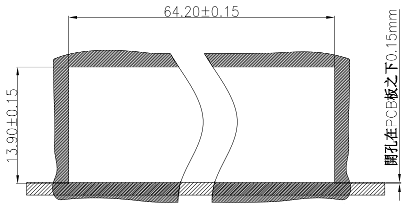
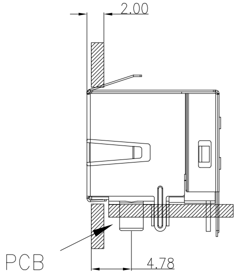
GP Component

| REV. | ECN NO. | LOCATIONS | DESCRIPTION | DATE | DESIGN |
|---|---|---|---|---|---|
| A0 | | | Initial | 2020/04/30 | H.QIU |
| A1 | | | Add D/C | 2026/01/06 | Vince |

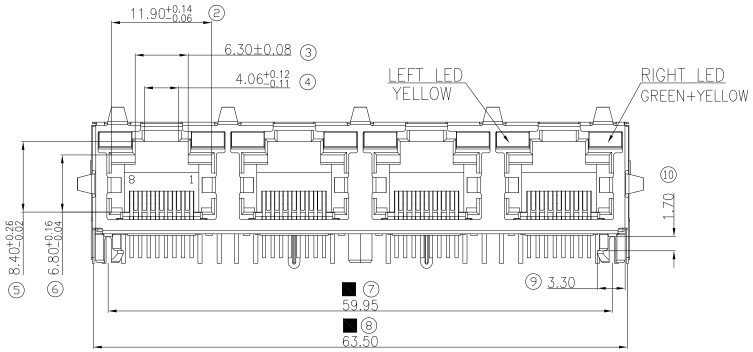


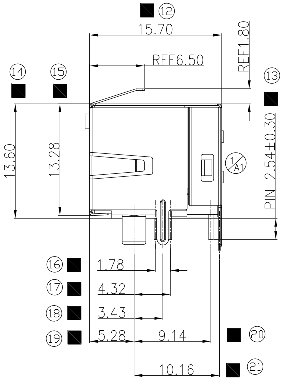


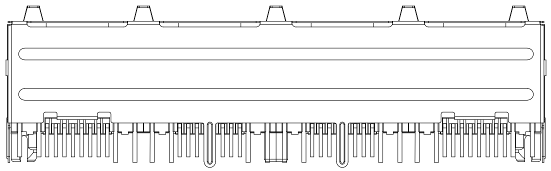
RECOMMENDED
PANEL CUTOUT DIMENSION

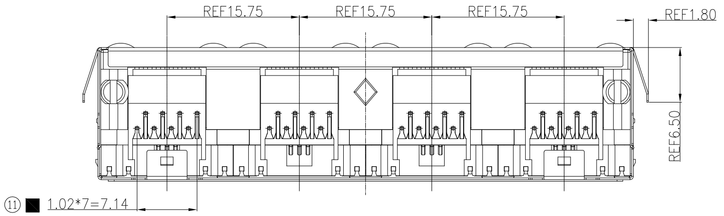


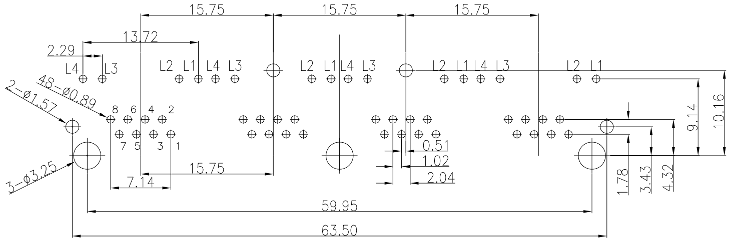
NOTES:
1.MATERIAL:
HOUSING:HIGH TEMP PA9T. THERMOPLASTIC, BLACK, UL 94V-0
CONTACT:PHOSPHOR BRONZE,T=0.30mm
SHELL:C2680,T=0.20mm
2.FINISH:
CONTACT:50u"MIN. NICKEL UNDERPLATING ALL AREA,
100u"MIN. TIN ON SOLDERTAILS,
GOLD PLATING ON CONTACT AREA 3u".
SHELL:30u"MIN. NICKEL UNDERPLATING ALL AREA
3.OPERATING TEMPERTURE:-40°C~+85°C.
STORAGE TEMPERTURE :-40°C~+85°C.
4.JACK CAVITY CONFORMS TO FCC RULES AND
REGULATIONS PART 68, SUBPART F
5.ELECTRICAL:
VOLTAGE RATING:125 VAC RMS.
COURRENT RATING: 1.5AMP.











PCB LAYOUT TOLERANCE:±0.05
TOP VIEW

Matrix Electronics Co.,Ltd

| | | | |
|---|---|---|---|
| TOLERANCE:<br>X.<br>X.X ±0.38<br>X.XX ±0.25<br>X.XXX ±0.13<br>X.° ±2° X.X° ±1° | DESIGN BY : Vince Chen | DATE : 2026/01/06 | PART NAME: RJ45 1X4 CONN,W/LED |
| | CHECKED BY: Hanson Huang | DATE : 2026/01/06 | PART NO. KRM-S-04-8-8-E-ME1-LN6 |
| UNIT: mm [inch] | APPROVED BY1: Richard Hsieh | DATE : 2026/01/06 | MOLD NO. NA |
| SCALE:1:1 SIZE:A4 | APPROVED BY2: Richard Hsieh | DATE : 2026/01/06 | DRAW NO.<br>SHEET NO. 1 OF 1 |